

WHAT IS CLAIMED IS:

1. A probe card for use in a performance test of a chip of a semiconductor device in a production process of the semiconductor device, the probe card comprising:

5 a plurality of probe pins for flowing a high current therethrough for the test, each of the probe pins having a balance resistance connected thereto in series, each balance resistance having a value greater than a contact resistance between each of the probe pins and a chip pad of
10 the semiconductor device which are brought into contact with each other; and

a plurality of contact check wires for checking a contact performance of each of the probe pins, wherein each of the contact check wires is drawn from a junction point
15 positioned between each of the probe pins and a corresponding balance resistance connected thereto.

2. The probe card as claimed in Claim 1, having a first connector electrode section for a performance test of
20 a chip and second connector electrode section for checking the probe card per se, wherein both of the first and second connector electrode sections are separately mounted on a substrate of the probe card.

25 3. The probe card as claimed in Claim 2, wherein the

first connector electrode section for the performance test of a chip and the second connector electrode section for checking the probe card have the same size and same shape with each other, and are mounted respectively at two
5 opposing side portions of the substrate of the probe card.